

ABSTRACT

The present invention relates to a substrate processing apparatus for processing a substrate, such as a wafer. The substrate processing apparatus (1) includes a substrate holder (5), a processing head (10), a tape take-up reel (22), a take-up reel rotating
5 mechanism (32), a tape outer diameter acquisition mechanism (70) configured to acquire an outer diameter of a roll (36) of a processing tape (2) taken up on the tape take-up reel (22), a rotary torque calculating section (72) configured to calculate a rotary torque required for taking up the processing tape (2) on tape take-up reel (22) with a predetermined tape tension based on the outer diameter, and an operation controller (60)
10 configured to control an operation of the take-up reel rotating mechanism (32). The operation controller (60) is configured to instruct the take-up reel rotating mechanism (32) to rotate the tape take-up reel (22) with the calculated rotary torque.

FIG. 1